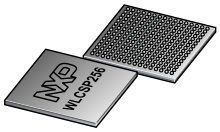
SOT2213-1

WLCSP256, wafer level chip-size package, 256 terminals, 0.35 mm pitch, 6.02 mm x 6.065 mm x 0.49 mm body

29 August 2025 Package information



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP256
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	S (silicon)
Mounting method type	S (surface mount)
Manufacturer package code	98ASA01940D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.99	6.02	6.05	mm
package width	6.035	6.065	6.095	mm
seated height	-	0.49	0.525	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	256	-	

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2 Package outline

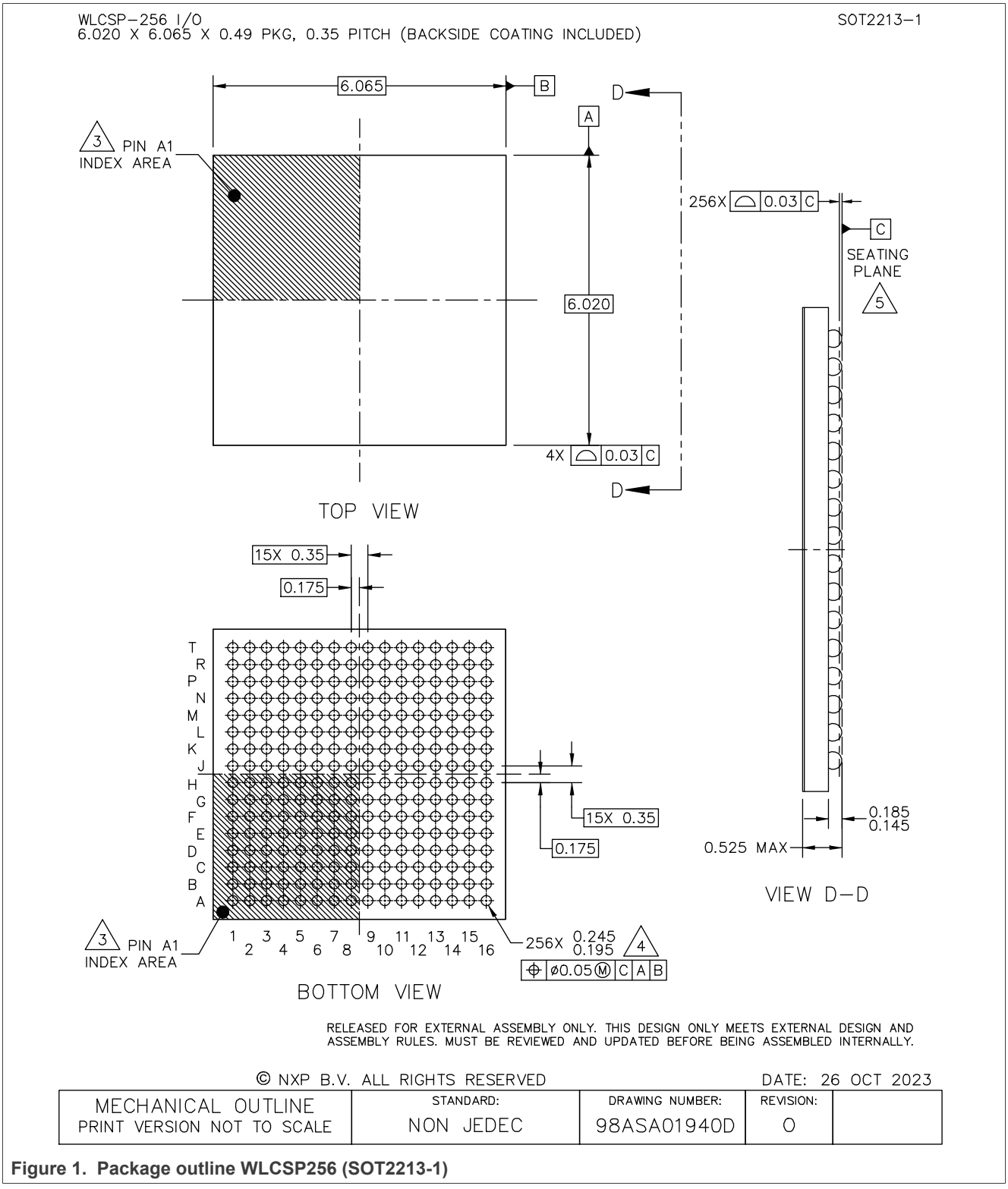

Figure 1. Package outline WLCSP256 (SOT2213-1)

3 Soldering

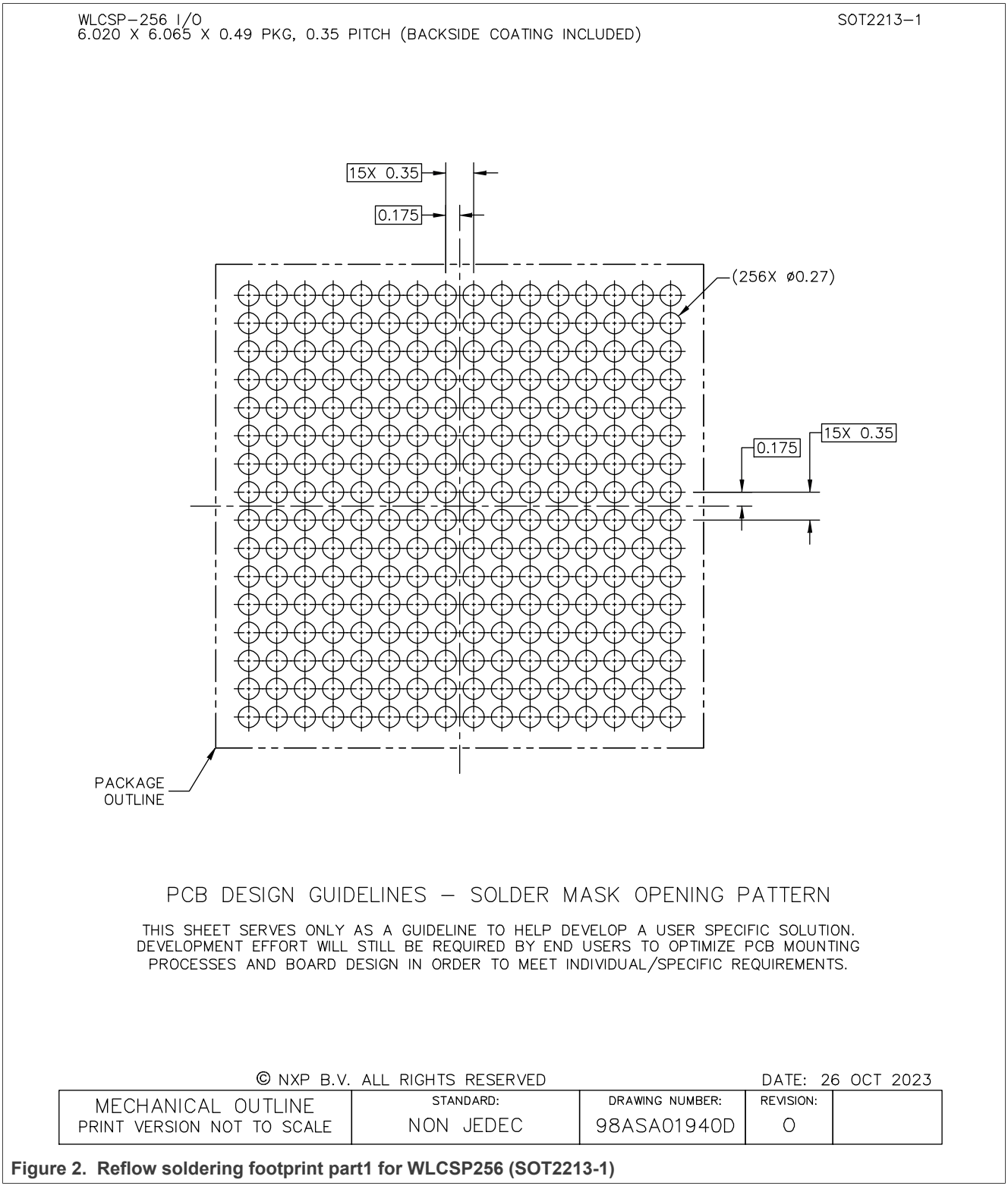

Figure 2. Reflow soldering footprint part1 for WLCSP256 (SOT2213-1)

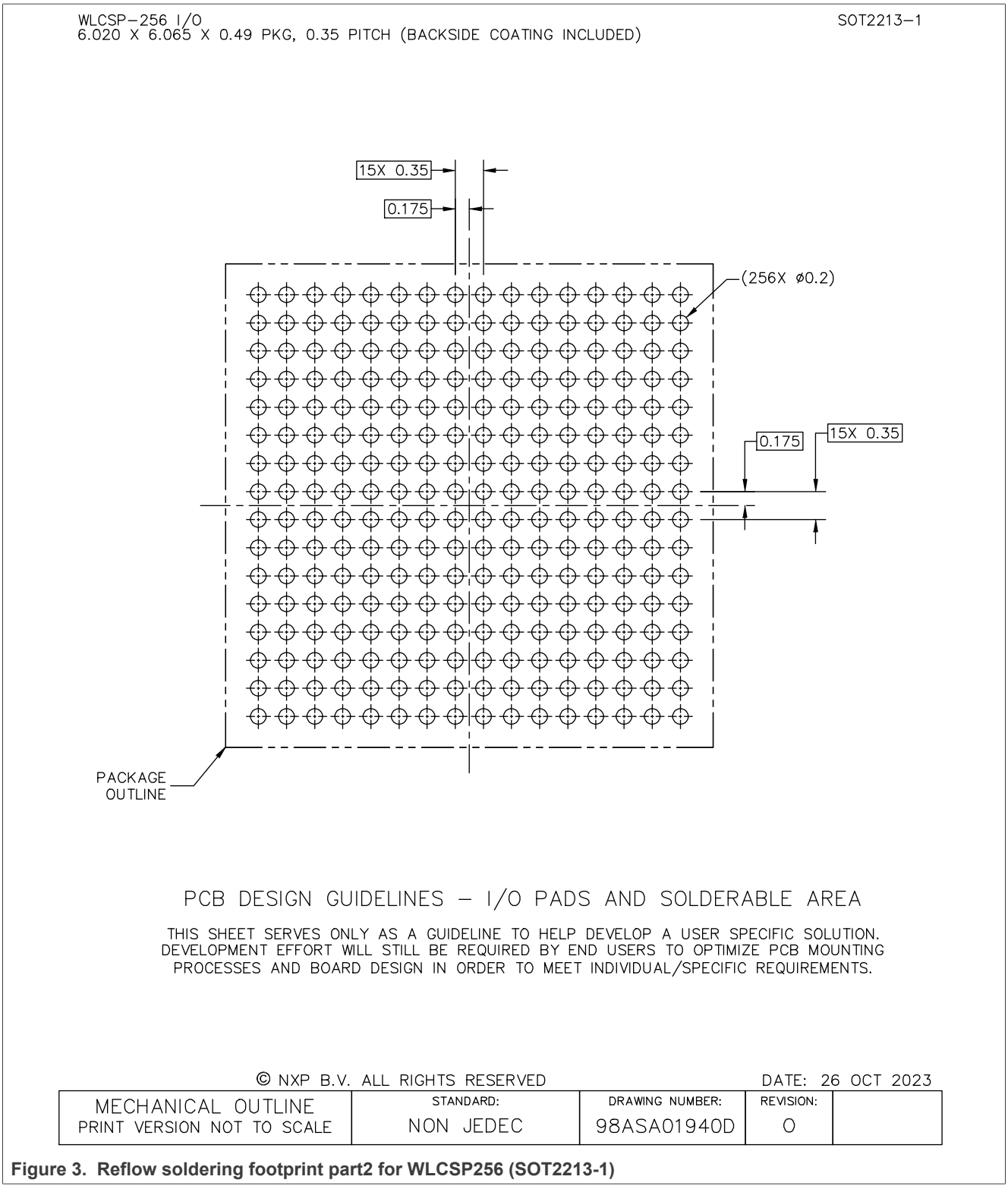

Figure 3. Reflow soldering footprint part2 for WLCSP256 (SOT2213-1)

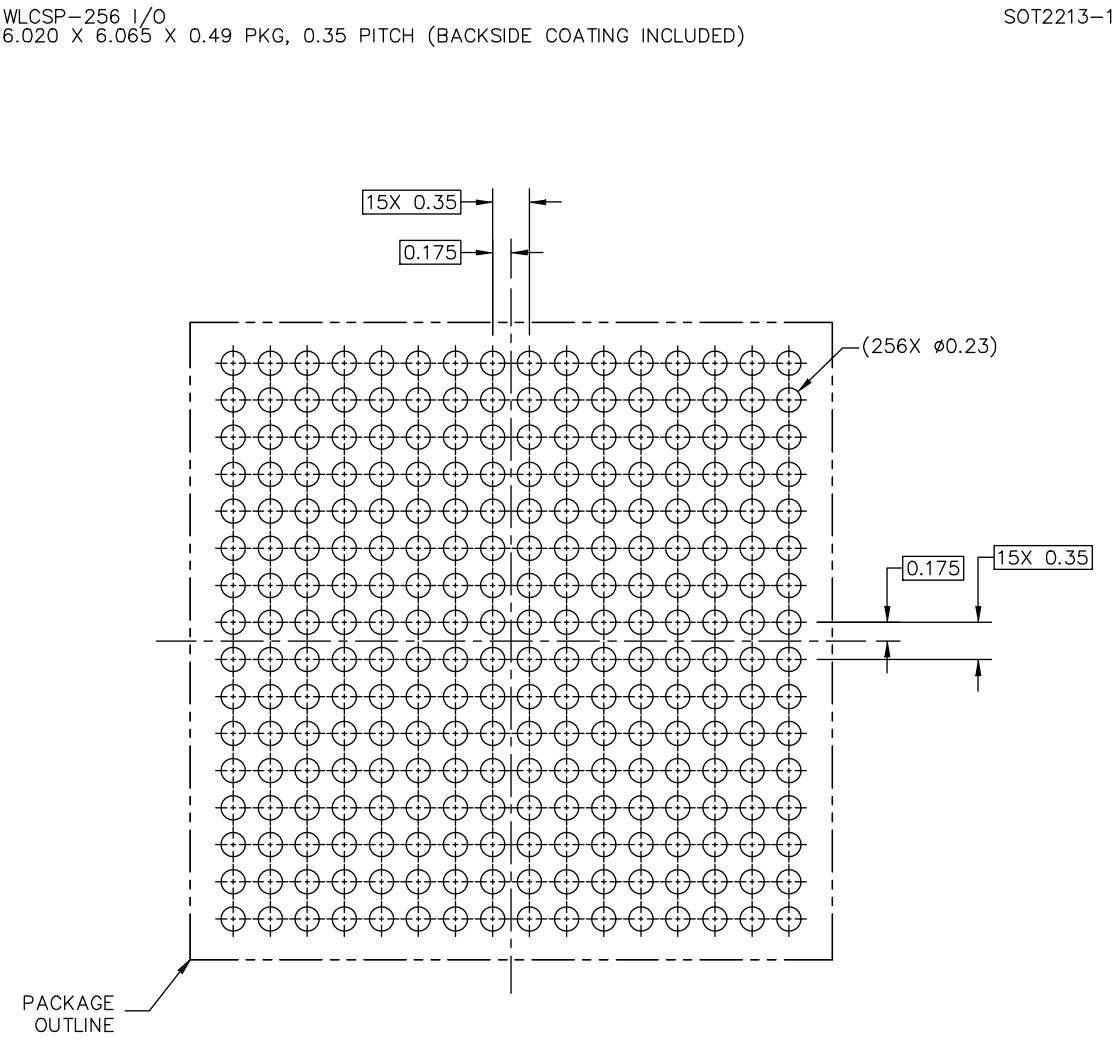

Figure 4. Reflow soldering footprint part3 for WLCSP256 (SOT2213-1)

WLCSP256, wafer level chip-size package, 256 terminals, 0.35 mm pitch, 6.02 mm x 6.065 mm x 0.49 mm body

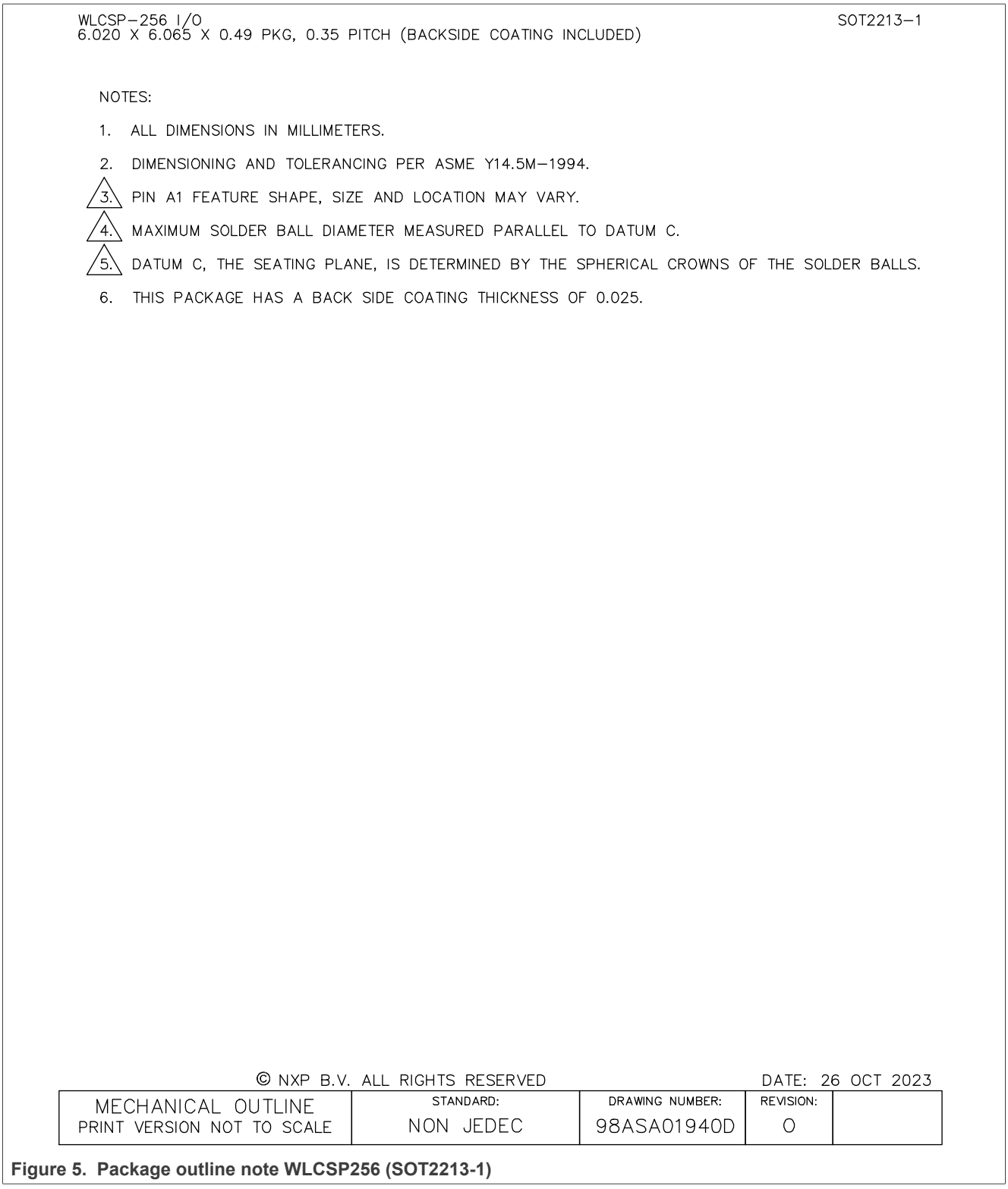

Figure 5. Package outline note WLCSP256 (SOT2213-1)

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